



0.8A SURFACE MOUNT GLASS PASSIVATED BRIDGE RECTIFIER

FEATURES:

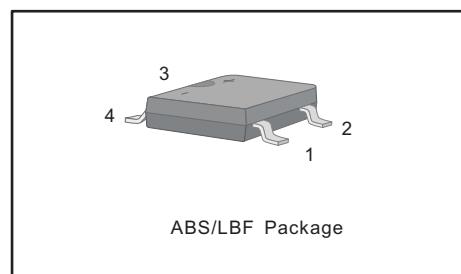
- Glass Passivated Chip Junction
- Reverse Voltage - 100 to 1000 V
- Forward Current - 0.8 A
- High Surge Current Capability
- Designed for Surface Mount Application

PINNING

PIN	DESCRIPTION
1	Input Pin (~)
2	Input Pin (~)
3	Output Anode (+)
4	Output Cathode (-)

MECHANICAL DATA

- Case: ABS/LBF
- Terminals: Solderable per MIL-STD-750, Method 2026
- Approx. Weight: 88mg / 0.0031oz



Maximum Ratings and Electrical characteristics

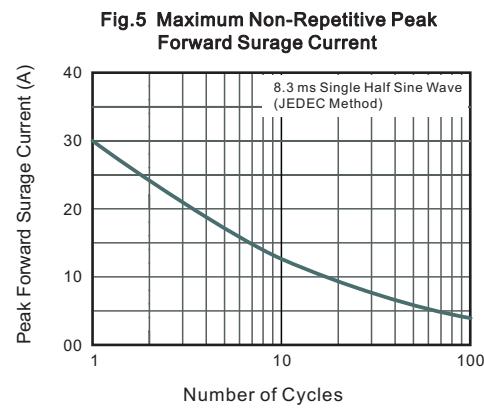
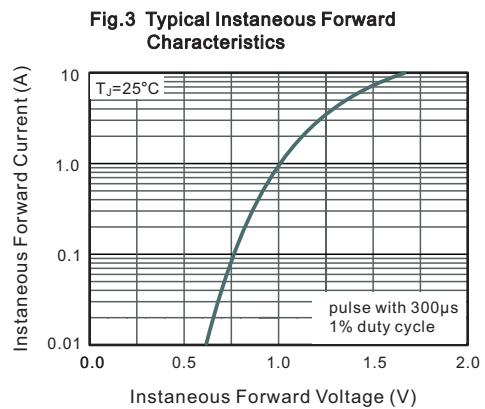
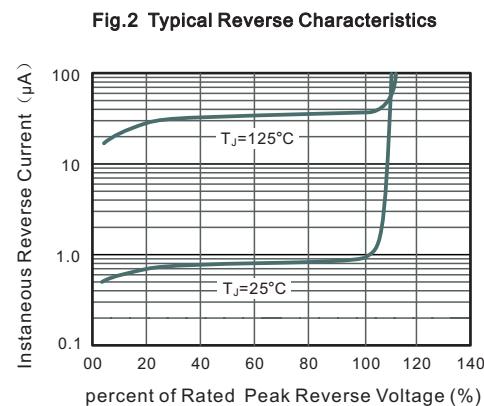
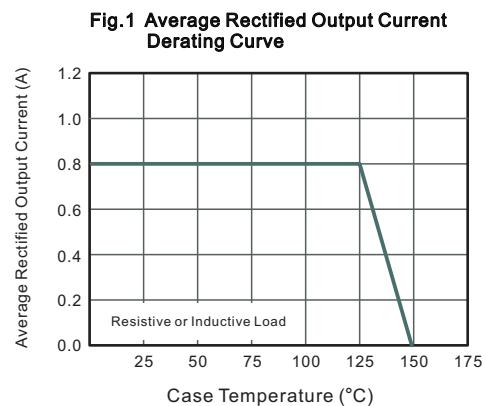
Ratings at 25 °C ambient temperature unless otherwise specified.

Single phase half-wave 60 Hz, resistive or inductive load, for capacitive load current derate by 20 %.

Parameter	Symbols	TB1S	TB2S	TB4S	TB6S	TB8S	TB10S	Units
Maximum Repetitive Peak Reverse Voltage	V _{RRM}	100	200	400	600	800	1000	V
Maximum RMS voltage	V _{RMS}	70	140	280	420	560	700	V
Maximum DC Blocking Voltage	V _{DC}	100	200	400	600	800	1000	V
Average Rectified Output Current at T _c = 125 °C	I _o	0.8						A
Peak Forward Surge Current 8.3 ms Single Half Sine Wave Superimposed on Rated Load (JEDEC Method)	I _{FSM}	30						A
Forward Voltage per element @I _f = 0.4A @I _f = 0.8A	V _F	1.0 1.1						V
Maximum DC Reverse Current @T _A =25 °C @T _A =100°C @T _A =125 °C	I _R	5.0 50 100						μA
Typical Thermal Resistance (Note2)	R _{θJA} R _{θJC}	80 22						°C/W
Operating and Storage Temperature Range	T _j , T _{stg}	-55 ~ +150						°C

Note: 1. Measured at 1MHz and applied reverse voltage of 4 V D.C.

2. Mounted on glass epoxy PC board with 4×1.5"×1.5" (3.81×3.81 cm) copper pad.

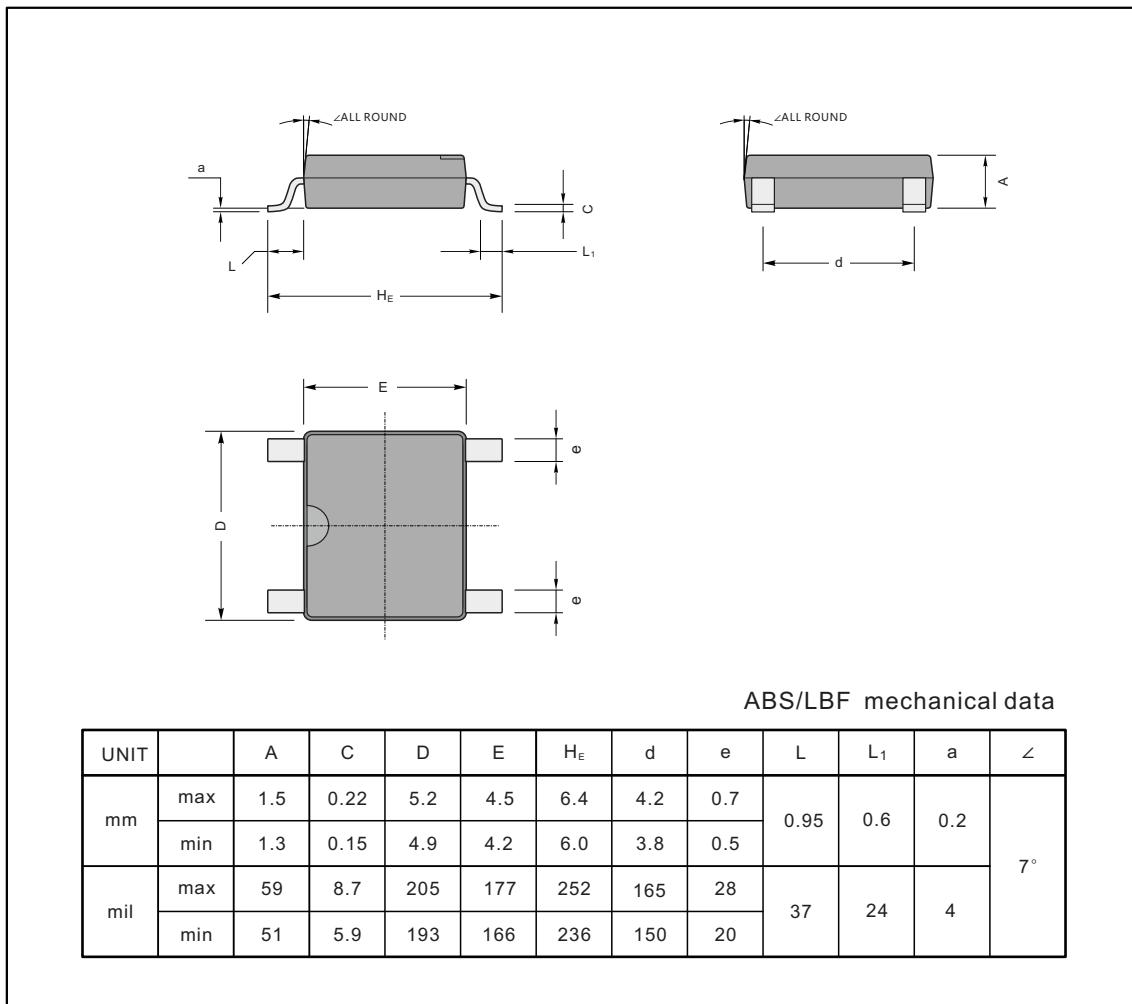




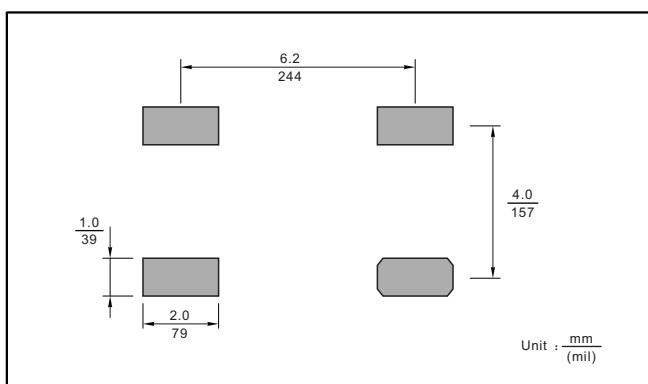
PACKAGE OUTLINE

Plastic surface mounted package; 4 leads

ABS/LBF



The recommended mounting pad size



Marking

Type number	Marking code
TB1S	TB1S
TB2S	TB2S
TB4S	TB4S
TB6S	TB6S
TB8S	TB8S
TB10S	TB10S

Marking code example: TBxxS